

## **CyberOptics Semiconductor WaferSense® Auto Gapping System (AGS300) Optimizes Wafer Processing Routines**

**Wilsonville, Oregon, June 11, 2008** – CyberOptics Semiconductor presents the WaferSense Auto Gapping System AGS 300 (<http://www.cyberopticssemi.com/products/wafersense/ags/>), a precision, wireless gap measurement tool that improves film uniformity and boosts yield by supporting accurate and repeatable setups in the semiconductor fabrication process.

Available in both 300 mm and 200 mm form factors, the WaferSense AGS 300 measures gaps that are critical to the outcome of semiconductor processes such as thin-film deposition, sputtering and etch. Consisting of three capacitive distance sensors, the wafer gapping system measures the gaps between shower heads and pedestals at three points that define a plane to ensure accurate and reproducible equipment setups. The AGS 300 measures gaps from 9 mm to 20 mm (0.35” to 0.79”) with  $\pm 25$  micron accuracy within 4 hours of field offset calibration. Using the AGS 300, engineers can better control gap uniformity and magnitude with high stability over time.

While legacy gap measurement methods employed a wired leveling device and crush blocks that were susceptible to instrument and operator variances, the AGS 300 provides wireless measurements with first film check rates to over 99% accuracy. There are no wires that can break after repeated use or misalign as a result of the vacuum pulling on wires. Its wafer-like design and height of only 7.5 mm also allows for automatic handling to speed equipment set ups, maintenance and troubleshooting. In addition, the wireless method is repeatable and gives engineers data to optimize preventive maintenance schedules and process controls.

Data can be displayed on a laptop or PC in real-time so that gaps can be quickly adjusted, reducing tool calibration time. Current gap measurements are compared against target goals, with gap tolerances displayed in numerical and graphical forms to simplify adjustments. Readings can be logged so that the same gap is set across all of tools for better tool-to-tool process uniformity.

The AGS300 is a part of CyberOptics’ WaferSense family of devices that also include the Airborne Particle Sensor, Auto Leveling System, Auto Vibration System and Auto Teach System. Each device is designed to optimize wafer processing routines.

**CyberOptics Semiconductor will feature its WaferSense® Auto Gapping System (AGS300) along with their full line of WaferSense wireless metrology devices during Semicon West in booth 911 South.**

For more information on the WaferSense AGS Auto Gapping System, please refer to the web site at <http://www.cyberopticssemi.com/> or contact sales at (503) 495-2200 for more information.

**About CyberOptics Semiconductor, Inc.**

CyberOptics Semiconductor develops automated products that seamlessly measure critical parameters in semiconductor fabrication processes and equipment. The company's pioneering WaferSense® line includes wireless metrology devices for vibration, leveling, gapping, teaching and sensing airborne particles in semiconductor process equipment. The company is the largest producer of reflective wafermapping sensors and a leading provider of frame grabber machine vision boards under its HAMA Sensors™ and Imagenation™ brands. CyberOptics Semiconductor is a subsidiary of CyberOptics Corp. (Nasdaq:CYBE), one of the world's leading providers of process yield and throughput improvement solutions for the electronic assembly and semiconductor fabrication industries. For information, visit <http://www.cyberopticssemi.com/>, e-mail [CSsales@cyberoptics.com](mailto:CSsales@cyberoptics.com) or call 800-366-9131.

**Contacts:**

CyberOptics Semiconductor, Inc.  
Lindsey Dietz  
503.495.2217  
[ldietz\[at\]cyberoptics.com](mailto:ldietz[at]cyberoptics.com)  
<http://www.cyberopticssemi.com/>

**9130 SW Pioneer Court, Suite D Wilsonville, OR 97070 USA**  
**Toll Free: 800.366.9131    Phone: 503.495.2200    Fax: 503.495.2201**